

Title (en)

SYSTEM AND METHOD FOR MONITORING PRESSURE DURING THE PRODUCTION OF FIBER REINFORCED POLYMERS

Publication

EP 0472590 A4 19920527 (EN)

Application

EP 90907685 A 19900504

Priority

US 34882289 A 19890508

Abstract (en)

[origin: WO9013425A1] Disclosed is a system and method of monitoring exerted pressure during the production of composite material laminates that utilizes a thin, low cost, durable, temperature resistant force sensing resistor (50). The sensor (50) can be embedded directly on the surface of the composite laminate (42), or can be positioned between layers of the composite laminate (42). Alternatively, the sensor (50) is built into or mounted on a tool (46) or die used to form or exert pressure on the laminate (42). In all of these cases, the force sensing resistor (50) monitors the pressure experienced by the laminate (42) during processing of the laminate (42).

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IPC 8 full level

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Citation (search report)

- [XO] SIXTH INTERNATIONAL ELECTRONIC MANUFACTURING TECHNOLOGY SYMPOSIUM, Nara, 26th - 28th April 1989 & IEEE TRANSACTIONS ON COMPONENTS, HYBRIDS, AND MANUFACTURING TECHNOLOGY, vol. 13, no. 2, June 1990, pages 435-439; Y. HATAMURA et al.: "Analysis of the dynamic phenomena during lamination of multilayer printed circuit board by the measurement of pressure distribution"
- See references of WO 9013425A1

Designated contracting state (EPC)

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